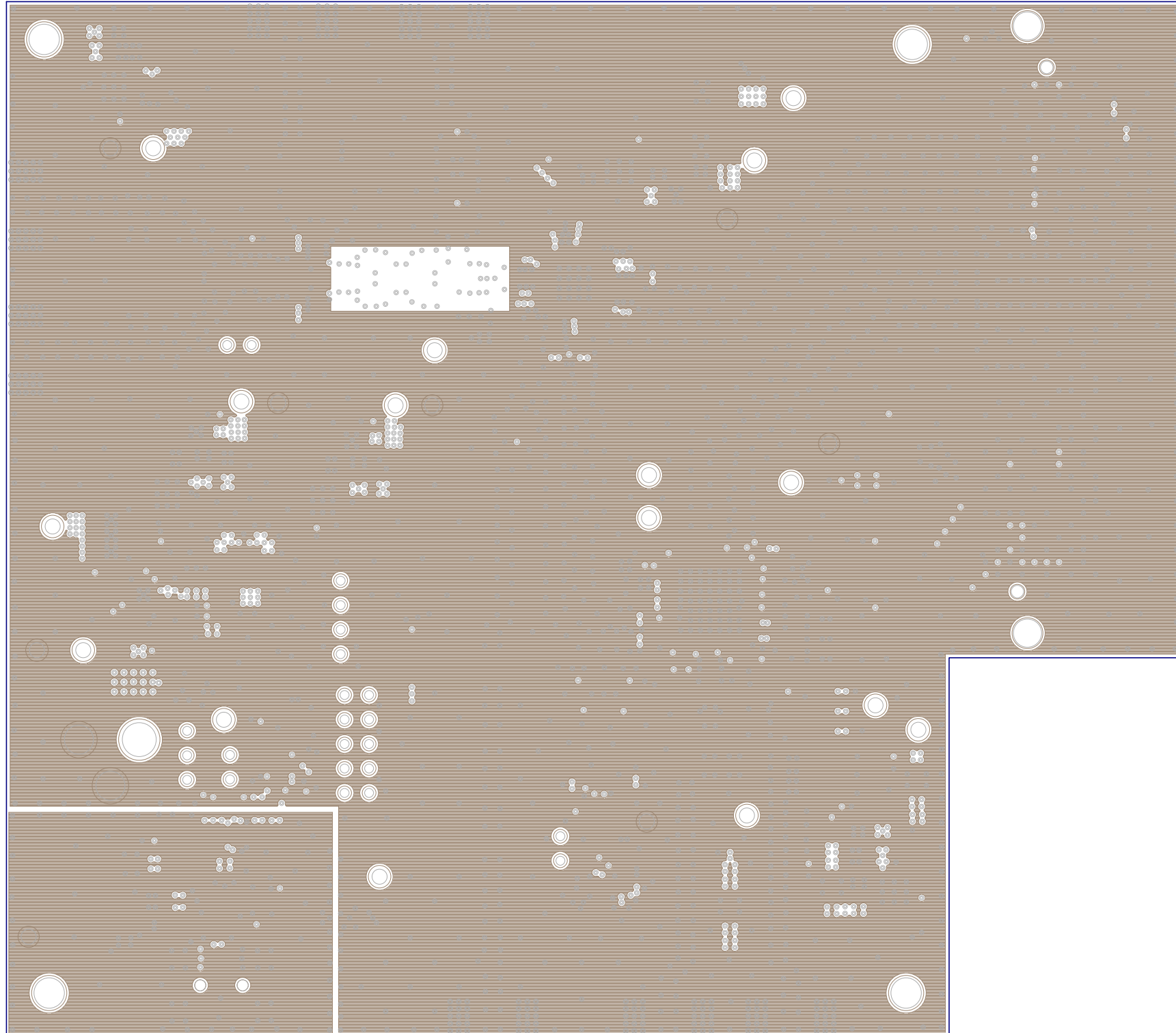
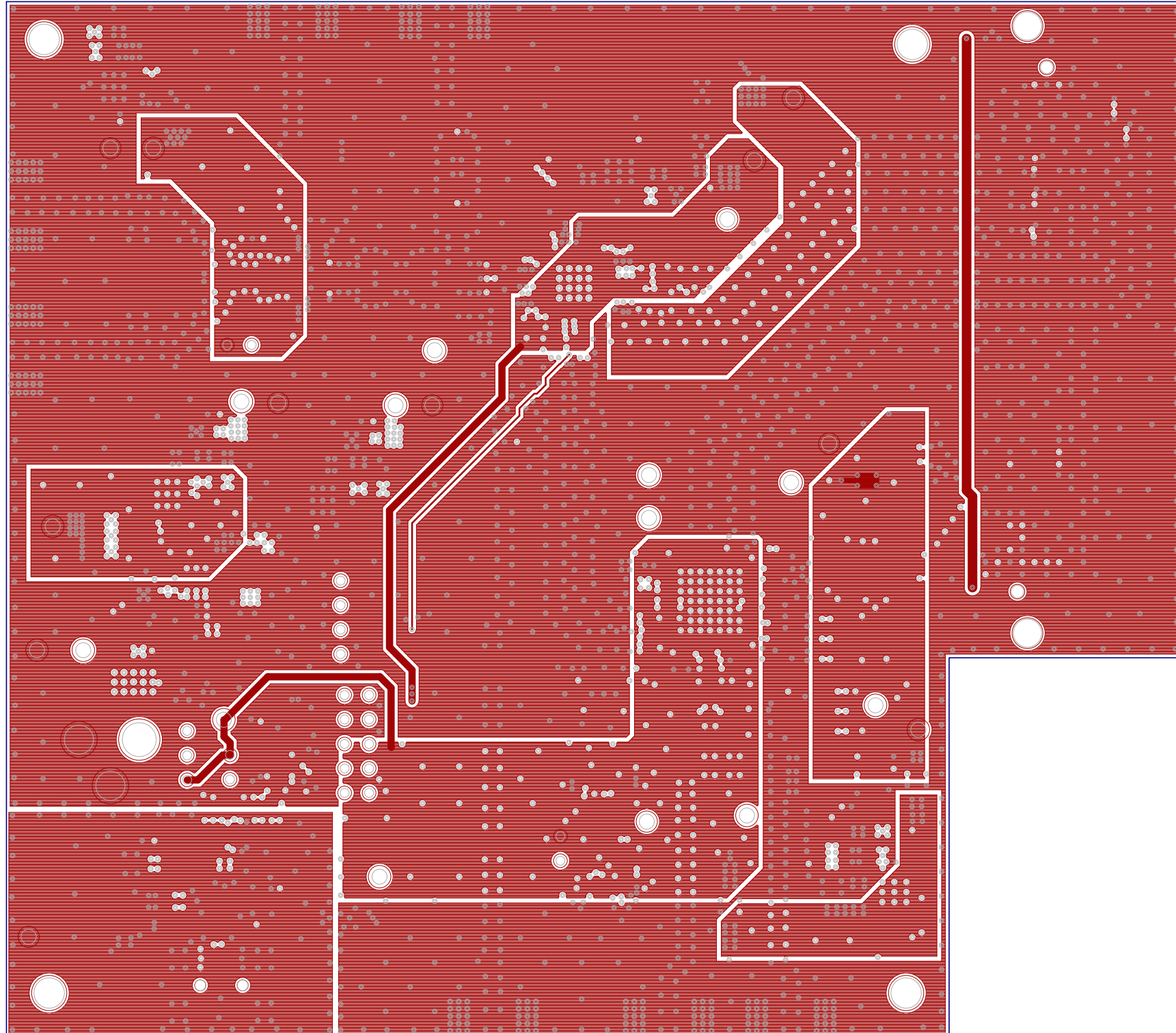


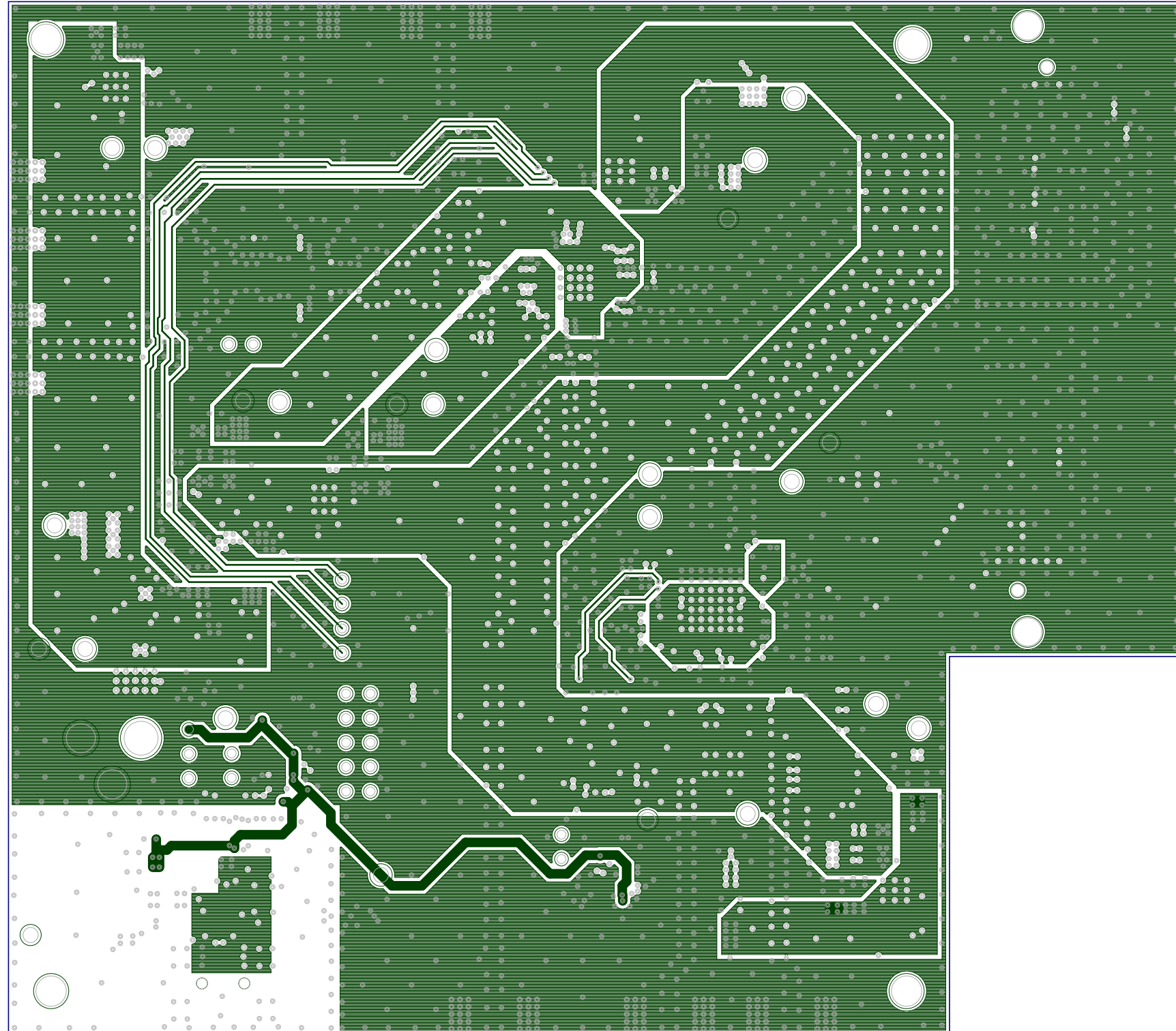
TEXAS INSTRUMENTS
 TSW14X500EVM
 PCB REV A
 SILKSCREEN TOP



TEXAS INSTRUMENTS
TSW14X500EVM
PCB REV A
L2 - GROUND PLANE



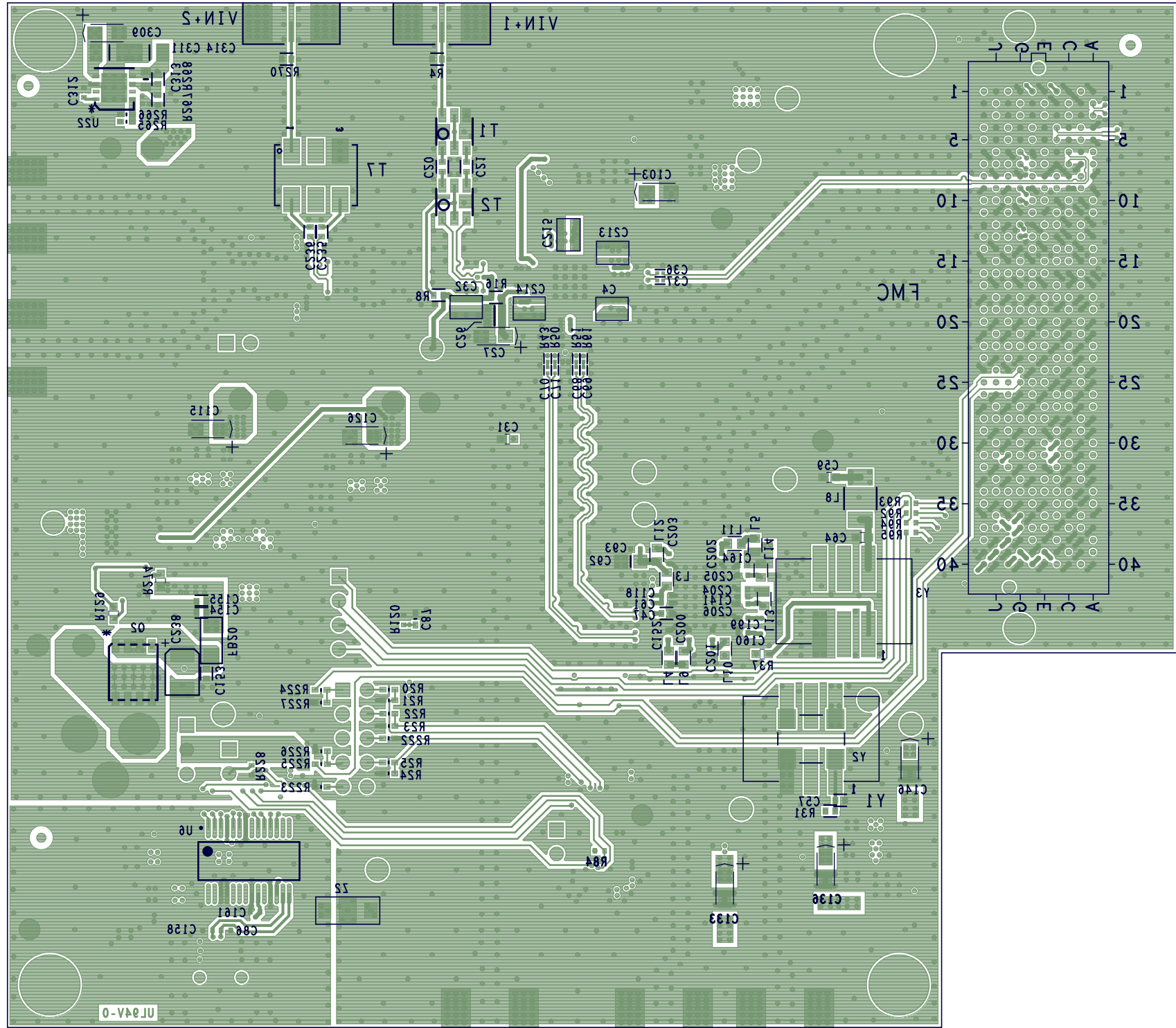
TEXAS INSTRUMENTS
TSW14X500EVM
PCB REV A
L3 - POWER PLANE



TEXAS INSTRUMENTS
TSW14X500EVM
PCB REV A
L4 - POWER PLANE



TEXAS INSTRUMENTS
TSW14X500EVM
PCB REV A
L5 - GROUND PLANE



TEXAS INSTRUMENTS
 TSW14X500EVM
 PCB REV A
 SILKSCREEN BOTTOM

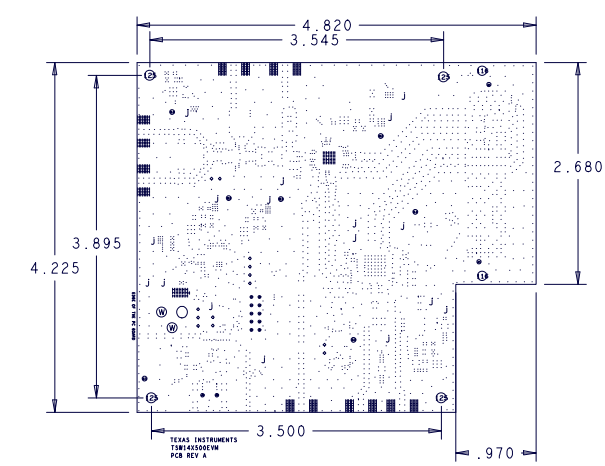
UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.
 NOTES PRECEDED BY AN UNMARKED "□" ARE NOT APPLICABLE.

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

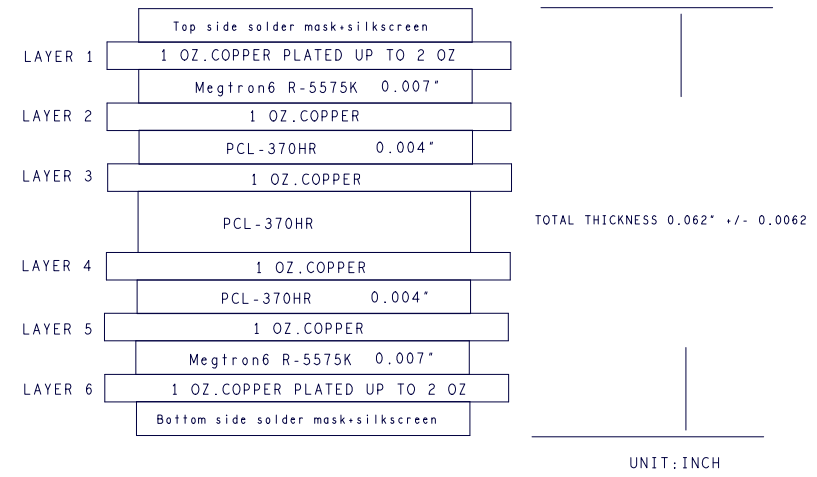
- APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS.
 IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
 IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
 IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
- HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE +/- .003.
- REGISTRATION TOLERANCE: ARTWORK +/- .002
 ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
 FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
 MATERIAL: □ SINGLE SIDED, □ DOUBLE SIDED, MULTI-LAYER (SEE DETAIL "A")
 SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: 0.062 +/- 10%
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT).
 COLOR=RED (0.001 TO 0.002" THICK OVER METAL).
- SILKSCREEN □ TOP SIDE BOTH SIDES. USING □ YELLOW WHITE NPI LEADFREE.
 REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH.
 MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

- ALL OUTER LAYERS USING A 13.00 mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/-10% TOLERANCE.
 □ ALL OUTER LAYERS USING A X.XX mil TRACE WIDTH SHALL BE 100ohms SINGLE ENDED, +/-10% TOLERANCE.
 □ ALL INNER LAYERS USING A X.XX mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/-10% TOLERANCE.
 □ ALL INNER LAYERS USING A X.XX mil TRACE WIDTH SHALL BE 100ohms SINGLE ENDED, +/-10% TOLERANCE.
 ALL OUTER LAYERS USING A 8.00 mil TRACE WIDTH AND 8.00 mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/-10% TOLERANCE.
 □ ALL INNER LAYERS USING A X.XX mil TRACE WIDTH AND X.XX mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/-10% TOLERANCE.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 5MIL.
 MINIMUM COPPER SPACING IS: 5MIL.
- SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 uIN NICKEL PLATING.
 □ SMOBC/HARD GOLD: 5-15 uIN OVER 100-200 uIN NICKEL PLATING.
- ALL THRU HOLE VIAS TO BE PLATED AND FILLED WITH NON-CONDUCTIVE EPOXY.
 FILLED VIAS SHALL BE PLATED AFTER FILLING AND COPLANOR.
- GROUND ETCH ON ALL LAYERS TO BOARD EDGE IS INTENTIONAL. DO NOT PULL BACK.
- NO CHANGES TO ANY ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.

DETAIL "A"



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
-	10.0	PLATED	2358
-	12.0	PLATED	32
-	12.01	PLATED	210
•	37.0	PLATED	10
•	38.0	PLATED	13
j	62.0	PLATED	17
•	63.0	PLATED	7
⊙	120.0	PLATED	2
⊙	125.0	PLATED	4
○	140.0	PLATED	1
•	46.0	NON-PLATED	2
•	51.0	NON-PLATED	2
⊙	116.0	NON-PLATED	2



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING TSW14X500EVM	
	DRAWN L. NGUYEN	07-02-14		
MATERIAL SEE NOTE 5	ENGR J. CARNES	SIZE B	CODE IDENT NO.	DRAWING NO.
FINISH SEE NOTES 7, 8, 9		SCALE NONE		REV. A
DO NOT SCALE DRAWING				SHEET 1 OF 1

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